

**HEX D-TYPE FLIP FLOP WITH CLEAR**

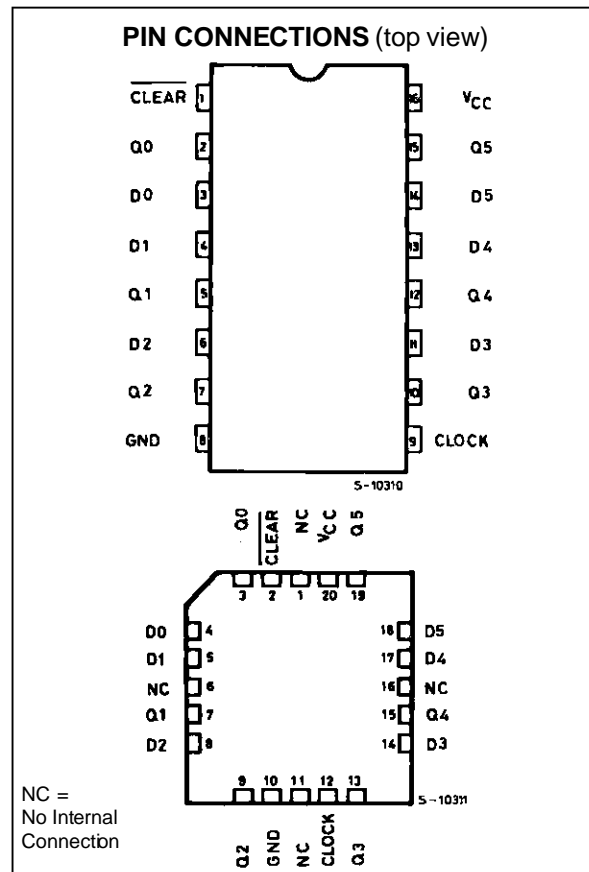
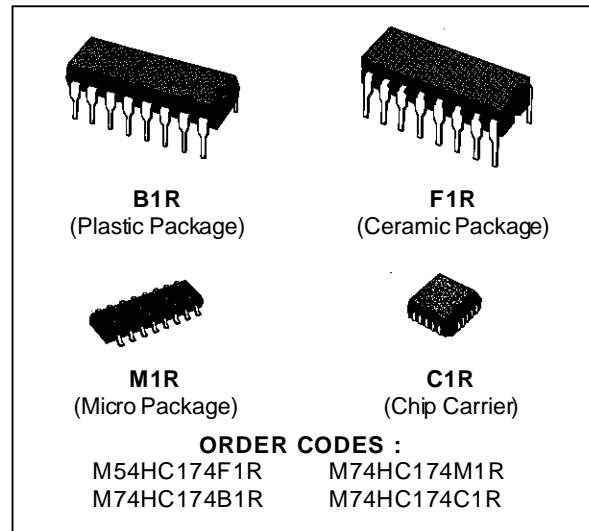
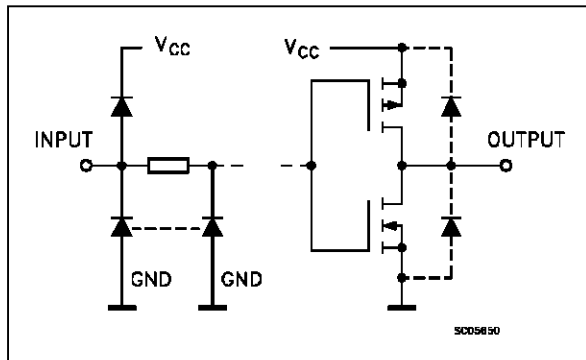
- HIGH SPEED  
f<sub>MAX</sub> = 71 MHz (TYP.) AT V<sub>CC</sub> = 5 V
- LOW POWER DISSIPATION  
I<sub>CC</sub> = 4 μA (MAX.) AT T<sub>A</sub> = 25 °C
- HIGH NOISE IMMUNITY  
V<sub>NIH</sub> = V<sub>NIL</sub> = 28 % V<sub>CC</sub> (MIN.)
- OUTPUT DRIVE CAPABILITY  
10 LSTTL LOADS
- SYMMETRICAL OUTPUT IMPEDANCE  
|I<sub>OH</sub>| = I<sub>OL</sub> = 4 mA (MIN.)
- BALANCED PROPAGATION DELAYS  
t<sub>PLH</sub> = t<sub>PHL</sub>
- WIDE OPERATING VOLTAGE RANGE  
V<sub>CC</sub> (OPR) = 2 V TO 6 V
- PIN AND FUNCTION COMPATIBLE WITH  
54/74LS174

**DESCRIPTION**

The M54/74HC174 is a high speed CMOS HEX D-TYPE FLIP-FLOP WITH CLEAR fabricated in silicon gate C<sup>2</sup>MOS technology. It has the same high speed performance of LSTTL combined with true CMOS low power consumption.

Information signals applied to D inputs are transferred to the Q output on the positive going edge of the clock pulse. When the CLEAR input is held low, the Q outputs are held low independently of the other inputs. All inputs are equipped with protection circuits against static discharge and transient excess voltage.

**INPUT AND OUTPUT EQUIVALENT CIRCUIT**



# M54/M74HC174

## TRUTH TABLE

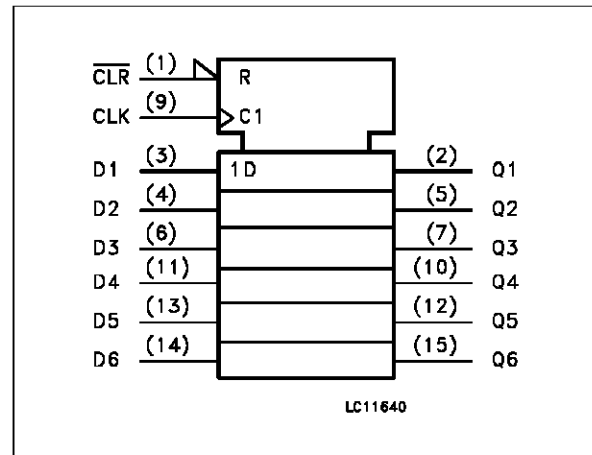
INPUTS			OUTPUTS	FUNCTION
CLEAR	D	CK	Q	
L	X	X	L	CLEAR
H	L		L	
H	H		H	
H	X		Q <sub>n</sub>	NO CHANGE

X: Don't Care

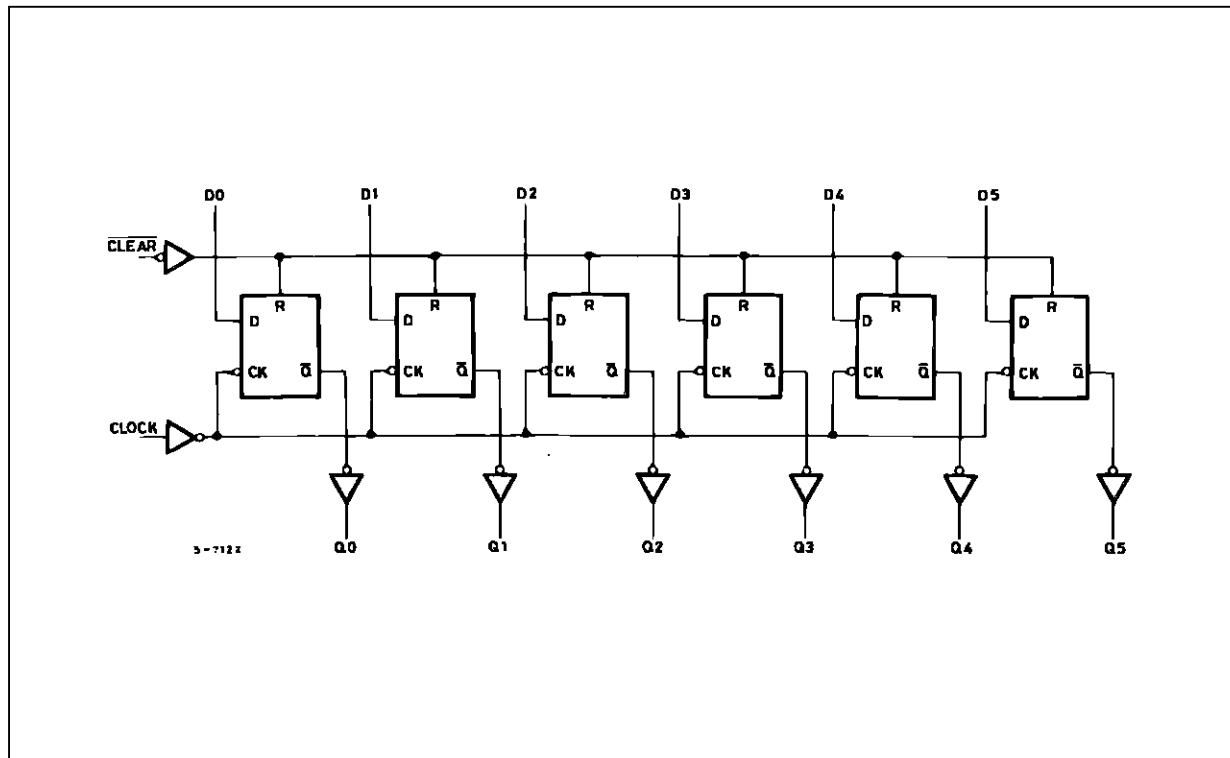
## PIN DESCRIPTION

PIN No	SYMBOL	NAME AND FUNCTION
1	CLEAR	Asynchronous Master Reset (Active LOW)
2, 5, 7, 10, 12, 15	Q0 to Q5	Flip-flop Outputs
3, 4, 6, 11, 13, 14	D0 to D5	Data Inputs
9	CLOCK	Clock Input (LOW to HIGH, edge triggered)
8	GND	Ground (0V)
16	V <sub>cc</sub>	Positive Supply Voltage

## IEC LOGIC SYMBOL



## LOGIC DIAGRAM



**ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	Supply Voltage	-0.5 to +7	V
V <sub>I</sub>	DC Input Voltage	-0.5 to V <sub>CC</sub> + 0.5	V
V <sub>O</sub>	DC Output Voltage	-0.5 to V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	DC Input Diode Current	± 20	mA
I <sub>OK</sub>	DC Output Diode Current	± 20	mA
I <sub>O</sub>	DC Output Source Sink Current Per Output Pin	± 25	mA
I <sub>CC</sub> or I <sub>GND</sub>	DC V <sub>CC</sub> or Ground Current	± 50	mA
P <sub>D</sub>	Power Dissipation	500 (*)	mW
T <sub>stg</sub>	Storage Temperature	-65 to +150	°C
T <sub>L</sub>	Lead Temperature (10 sec)	300	°C

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these condition is not implied.

(\*) 500 mW: ≅ 65 °C derate to 300 mW by 10mW/°C: 65 °C to 85 °C

**RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Value	Unit	
V <sub>CC</sub>	Supply Voltage	2 to 6	V	
V <sub>I</sub>	Input Voltage	0 to V <sub>CC</sub>	V	
V <sub>O</sub>	Output Voltage	0 to V <sub>CC</sub>	V	
T <sub>op</sub>	Operating Temperature: <b>M54HC Series</b> <b>M74HC Series</b>	-55 to +125 -40 to +85	°C °C	
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time	V <sub>CC</sub> = 2 V V <sub>CC</sub> = 4.5 V V <sub>CC</sub> = 6 V	0 to 1000 0 to 500 0 to 400	ns

**DC SPECIFICATIONS**

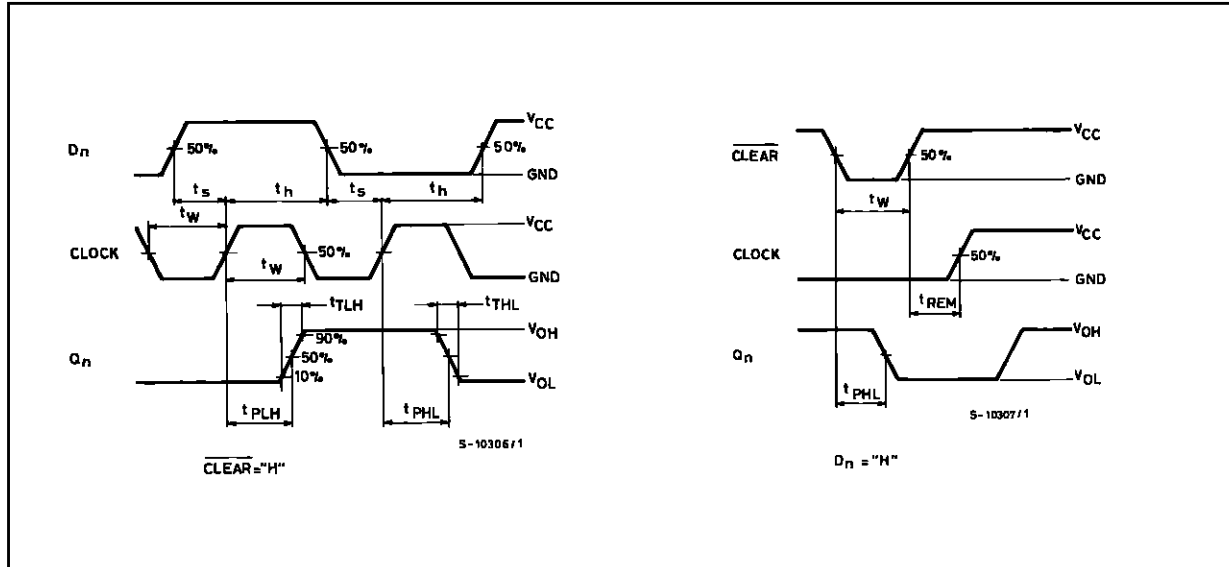
Symbol	Parameter	Test Conditions		Value						Unit		
		V <sub>CC</sub> (V)		T <sub>A</sub> = 25 °C 54HC and 74HC			-40 to 85 °C 74HC		-55 to 125 °C 54HC			
				Min.	Typ.	Max.	Min.	Max.	Min.		Max.	
V <sub>IH</sub>	High Level Input Voltage	2.0		1.5			1.5		1.5		V	
		4.5		3.15			3.15		3.15			
		6.0		4.2			4.2		4.2			
V <sub>IL</sub>	Low Level Input Voltage	2.0				0.5		0.5		0.5	V	
		4.5				1.35		1.35		1.35		
		6.0				1.8		1.8		1.8		
V <sub>OH</sub>	High Level Output Voltage	2.0	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>O</sub> = -20 μA	1.9	2.0		1.9		1.9	V	
		4.5			4.4	4.5		4.4		4.4		
		6.0			5.9	6.0		5.9		5.9		
		4.5	I <sub>O</sub> = -4.0 mA	4.18	4.31		4.13		4.10			
		6.0		I <sub>O</sub> = -5.2 mA	5.68	5.8		5.63		5.60		
V <sub>OL</sub>	Low Level Output Voltage	2.0	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>O</sub> = 20 μA		0.0	0.1		0.1		0.1	V
		4.5				0.0	0.1		0.1		0.1	
		6.0				0.0	0.1		0.1		0.1	
		4.5		I <sub>O</sub> = 4.0 mA	0.17	0.26		0.33		0.40		
		6.0			I <sub>O</sub> = 5.2 mA	0.18	0.26		0.33		0.40	
I <sub>I</sub>	Input Leakage Current	6.0	V <sub>I</sub> = V <sub>CC</sub> or GND			±0.1		±1		±1	μA	
I <sub>CC</sub>	Quiescent Supply Current	6.0	V <sub>I</sub> = V <sub>CC</sub> or GND			4		40		80	μA	

AC ELECTRICAL CHARACTERISTICS ( $C_L = 50$  pF, Input  $t_r = t_f = 6$  ns)

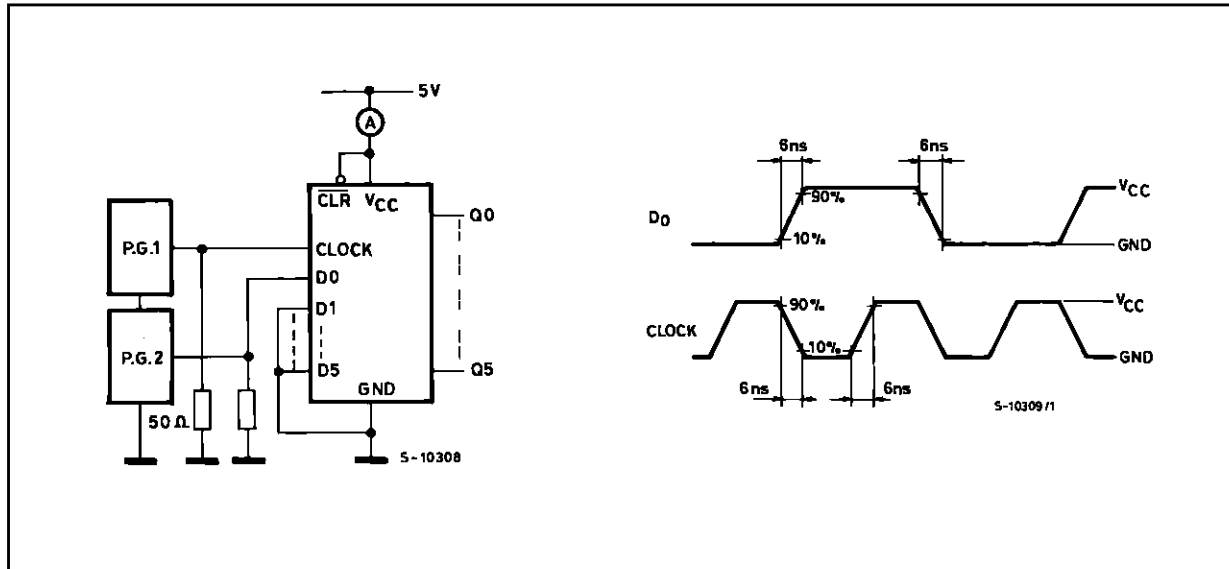
Symbol	Parameter	Test Conditions		Value						Unit	
		V <sub>CC</sub> (V)		T <sub>A</sub> = 25 °C 54HC and 74HC			-40 to 85 °C 74HC		-55 to 125 °C 54HC		
				Min.	Typ.	Max.	Min.	Max.	Min.		Max.
t <sub>TLH</sub> t <sub>THL</sub>	Output Transition Time	2.0			30	75		95		110	ns
		4.5			8	15		19		22	
		6.0			7	13		16		19	
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation Delay Time (CK - Q)	2.0			68	135		170		205	ns
		4.5			17	27		34		41	
		6.0			14	23		29		35	
t <sub>PHL</sub>	Propagation Delay Time (CLR - Q)	2.0			72	145		180		220	ns
		4.5			18	29		36		44	
		6.0			15	25		31		37	
f <sub>MAX</sub>	Maximum Clock Frequency	2.0		7.2	14		5.8		4.8		MHz
		4.5		36	56		29		24		
		6.0		42	66		34		28		
t <sub>W(H)</sub> t <sub>W(L)</sub>	Minimum Pulse Width (CLOCK)	2.0			24	75		95		110	ns
		4.5			6	15		19		22	
		6.0			5	13		16		19	
t <sub>W(L)</sub>	Minimum Pulse Width (CLR)	2.0			24	75		95		110	ns
		4.5			6	15		19		22	
		6.0			5	13		16		19	
t <sub>s</sub>	Minimum Set-up Time	2.0			28	75		95		110	ns
		4.5			7	15		19		22	
		6.0			6	13		16		19	
t <sub>h</sub>	Minimum Hold Time	2.0				0		0		0	ns
		4.5				0		0		0	
		6.0				0		0		0	
t <sub>REM</sub>	Minimum Removal Time	2.0			5	5		5		5	ns
		4.5			5	5		5		5	
		6.0			5	5		5		5	
C <sub>IN</sub>	Input Capacitance				5	10		10		10	pF
C <sub>PD</sub> (*)	Power Dissipation Capacitance				40						pF

(\*) C<sub>PD</sub> is defined as the value of the IC's internal equivalent capacitance which is calculated from the operating current consumption without load. (Refer to Test Circuit). Average operating current can be obtained by the following equation.  $I_{CC(opr)} = C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC}/6$  (per FLIP/FLOP)  
And the total CPD when N pcs of FLIP FLOP operate can be gained by the following equation: CPD (total) = 38 + 15 x n

SWITCHING CHARACTERISTICS TEST WAVEFORM

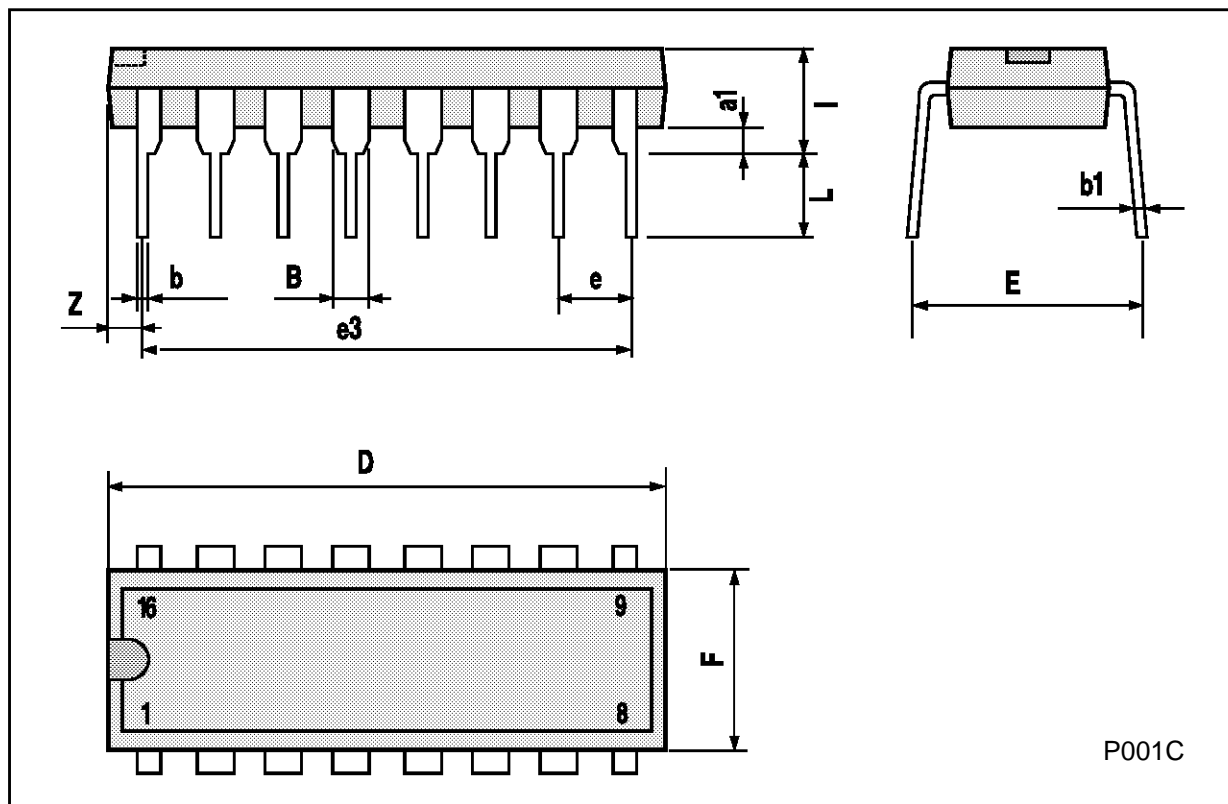


TEST CIRCUIT I<sub>cc</sub> (Opr.)



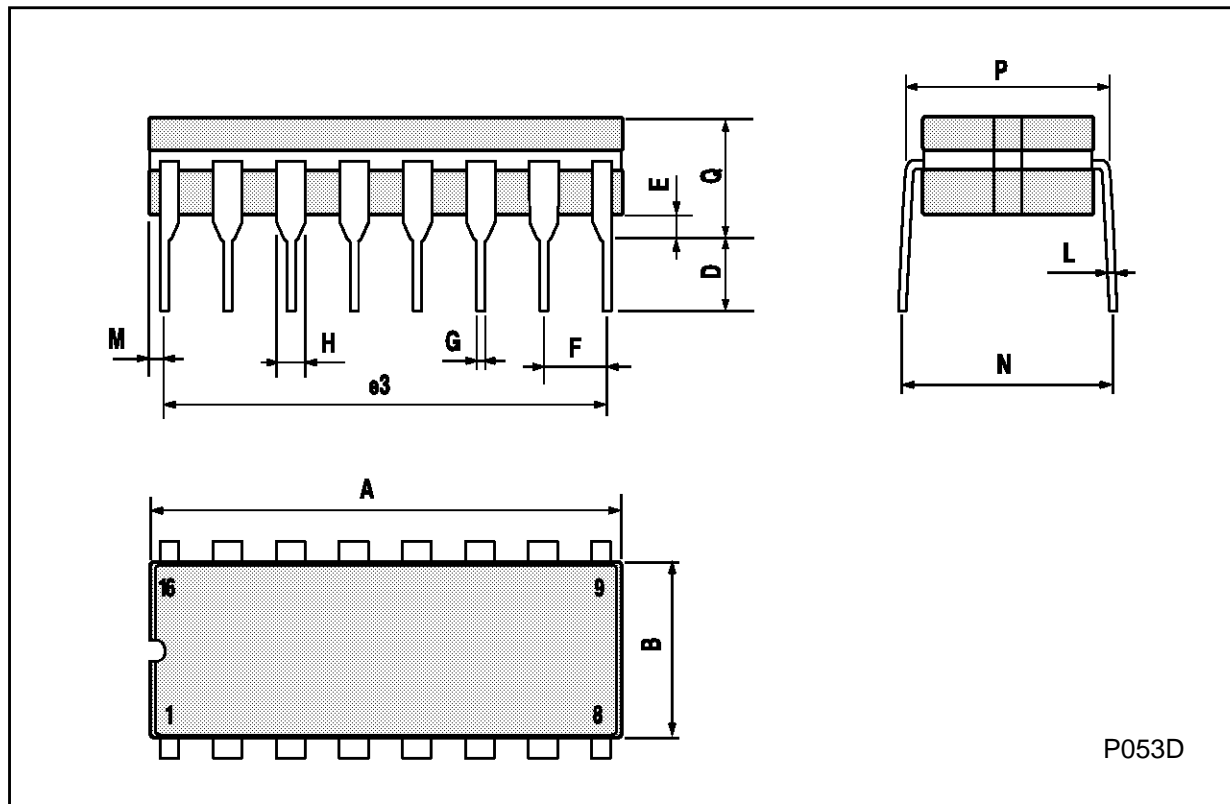
## Plastic DIP16 (0.25) MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
a1	0.51			0.020		
B	0.77		1.65	0.030		0.065
b		0.5			0.020	
b1		0.25			0.010	
D			20			0.787
E		8.5			0.335	
e		2.54			0.100	
e3		17.78			0.700	
F			7.1			0.280
I			5.1			0.201
L		3.3			0.130	
Z			1.27			0.050



Ceramic DIP16/1 MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			20			0.787
B			7			0.276
D		3.3			0.130	
E	0.38			0.015		
e3		17.78			0.700	
F	2.29		2.79	0.090		0.110
G	0.4		0.55	0.016		0.022
H	1.17		1.52	0.046		0.060
L	0.22		0.31	0.009		0.012
M	0.51		1.27	0.020		0.050
N			10.3			0.406
P	7.8		8.05	0.307		0.317
Q			5.08			0.200





## SO16 (Narrow) MECHANICAL DATA

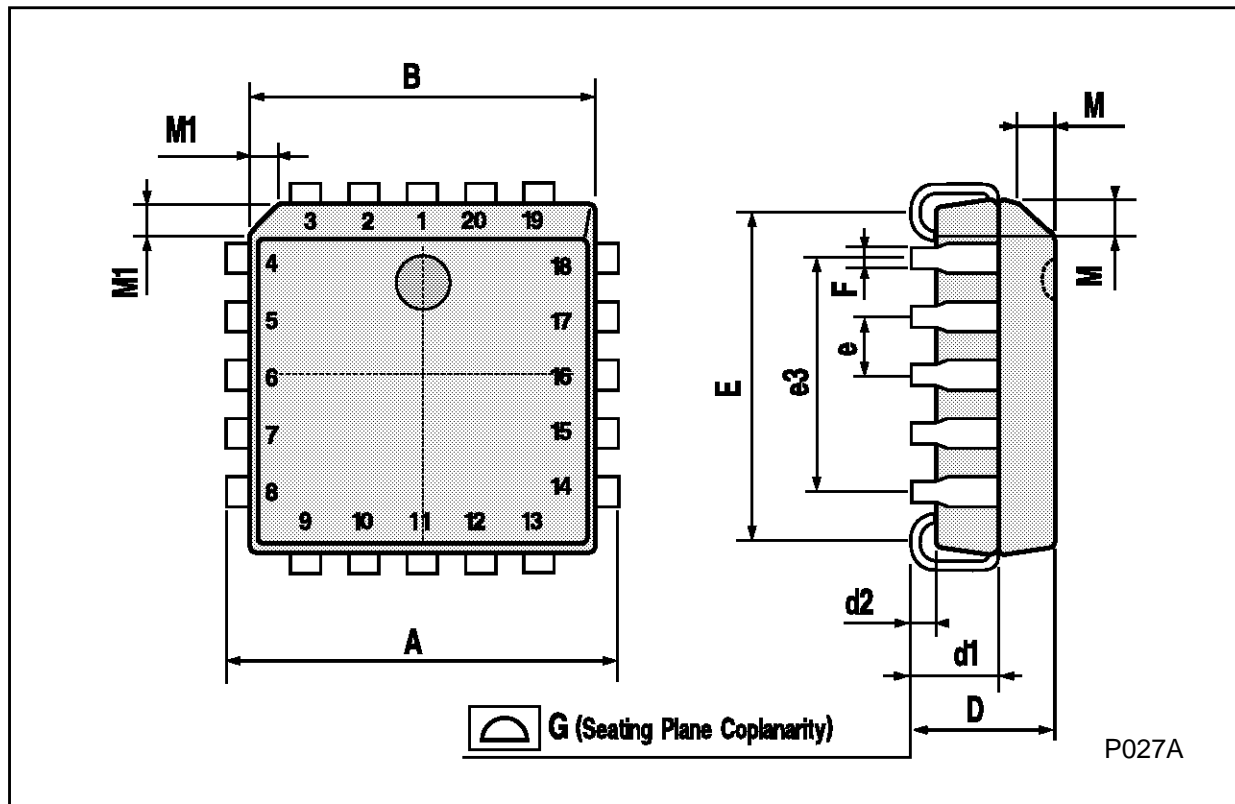
DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			1.75			0.068
a1	0.1		0.2	0.004		0.007
a2			1.65			0.064
b	0.35		0.46	0.013		0.018
b1	0.19		0.25	0.007		0.010
C		0.5			0.019	
c1	45° (typ.)					
D	9.8		10	0.385		0.393
E	5.8		6.2	0.228		0.244
e		1.27			0.050	
e3		8.89			0.350	
F	3.8		4.0	0.149		0.157
G	4.6		5.3	0.181		0.208
L	0.5		1.27	0.019		0.050
M			0.62			0.024
S	8° (max.)					



P013H

**PLCC20 MECHANICAL DATA**

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	9.78		10.03	0.385		0.395
B	8.89		9.04	0.350		0.356
D	4.2		4.57	0.165		0.180
d1		2.54			0.100	
d2		0.56			0.022	
E	7.37		8.38	0.290		0.330
e		1.27			0.050	
e3		5.08			0.200	
F		0.38			0.015	
G			0.101			0.004
M		1.27			0.050	
M1		1.14			0.045	



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